Simple search form Expanded search form

Search Results:

Search for:

(aluminum nitride)

Database:

Electronic Journals

Returned:

50 documents (Maximum set to: 50)

Click on the icon at the end of each title to find similar documents.

Ab initio tensile testing simulation of aluminum and aluminum nitride ceramics based on density functional theory (Computational Materials Science, Volume: 15, Issue: 4)

Ogata, Shigenobu, Kitagawa, Hiroshi, pp. 435-440,

Article Full-text PDF (173 KB)

Score: 100, November 1999

The microstructure and properties of a buried AlN layer produced by nitrogen implantation into pure aluminum (Thin Solid Films, Volume: 289, Issue: 1-2)

Lu, H.L.; Sommer, W.F.; Borden, M.J.; Tesmer, J.R.; Wu, X.D., pp. 17-21,
 Article Full-text PDF (506 KB)

Score: 85, November 30, 1996

Tunnel barrier growth dynamics of Nb/AlO_x-Al/Nb and Nb/AlN_x-Al/Nb Josephson junctions (Physica - C - Superconductivity, Volume: 241, Issue: 1/2)

• Neuhaus, M.; Jutzi, W.; Dolata, R., pp. 25-29, Article Full-text PDF (363 KB) Score: 78, January 1, 1995

Monte carlo simulation of electron transport in wurtzite aluminum nitride (Solid State Communications, Volume: 105, Issue: 10)

Bhapkar, U.V.; Foutz, B.E.; Eastman, L.F.; O'Leary, S.K.; Shur, M.S., pp. 621-626, Article Full-text PDF (578 KB)
 Score: 60, March 1998

Impurity Study of Alumina and Aluminum Nitride Ceramics: Microelectronics Packaging Applications (Applied Radiation and Isotopes, Volume: 48, Issue: 1)

 Kerness, N. D.; Hossain, T. Z.; McGuire, S. C., pp. 5-9, Article Full-text PDF (367 KB)

Score: 57, January 1997

Physical vapor deposition tool coatings (Surface and Coatings Technology, Volume: 81, Issue: 1)

• Sproul, W.D., pp. 1-7, Article Full-text PDF (812 KB)
Score: 57, May 1996

Low temperature nitridation of transition metals with hydrazine (Thin Solid Films, Volume: 256, Issue: 1/2)

o Vogt, K.W.; Naugher, L.A.; Kohl, P.A., pp. 106-115,



(aluminum <and>nitride)

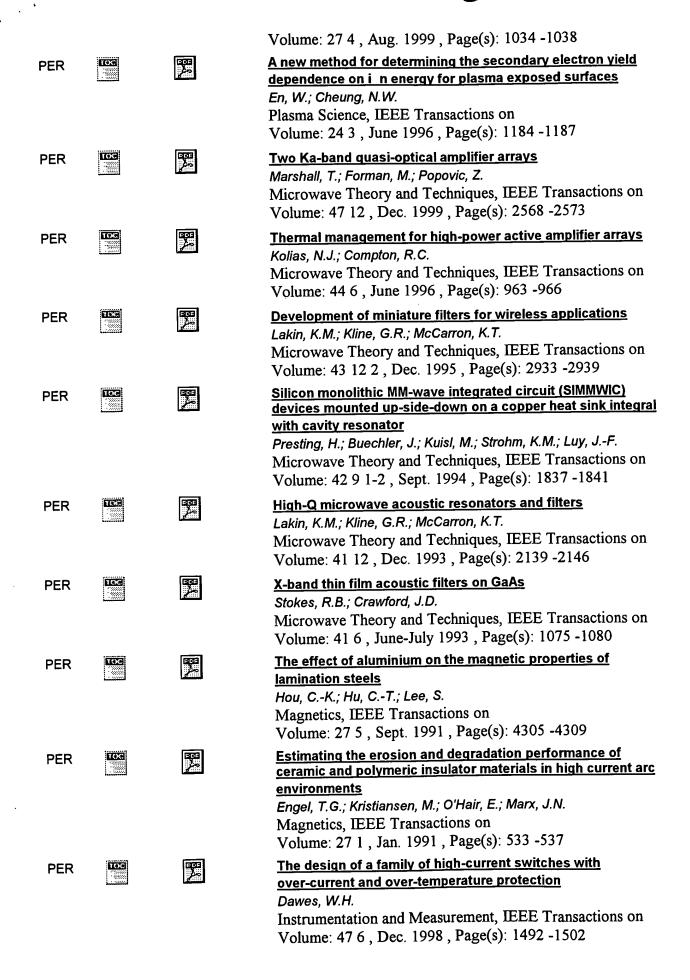
Refine

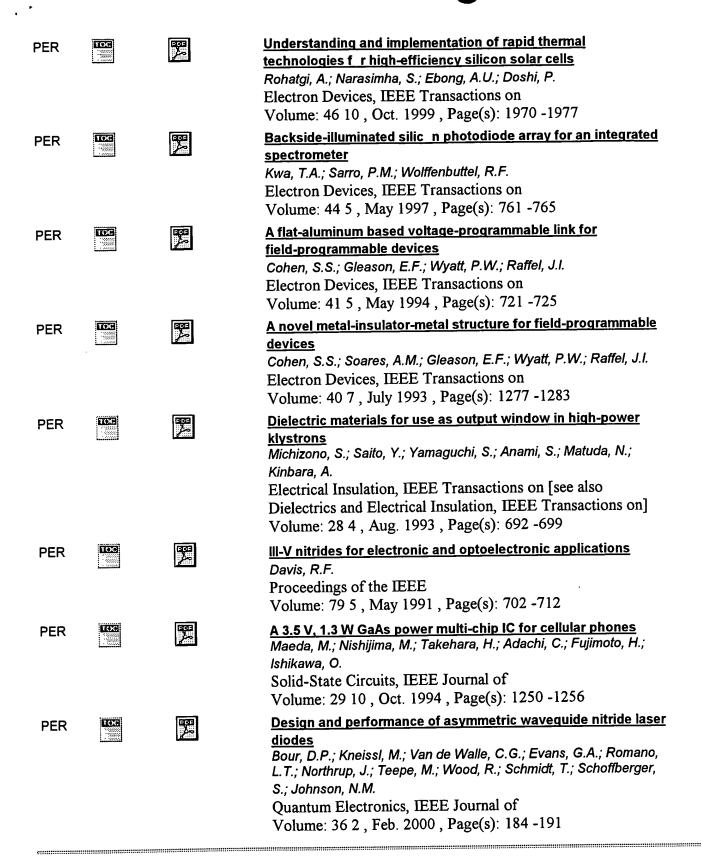
Collection: ☑ Journals ☑ Conferences ☑ Standards

Your search matched 198 of 623335 documents.

23 are presented on this page, sorted by Score in descending order.

DOC TYPE	VIEW ISSUE TOC	VIEW FULL PAGE	<u>VIEW CITATION</u>
PER			High thermal conductivity aluminum nitride ceramic substrates and packages Miyashiro, F.; Iwase, N.; Tsuge, A.; Ueno, F.; Nakahashi, M.; Takahashi, T. Components, Hybrids, and Manufacturing Technology, IEEE Transactions on [see also IEEE Trans. on Components, Packaging, and Manufacturing Technology, Part A, B, C] Volume: 13 2, June 1990, Page(s): 313-319
PER	1155		Aq-Pd thick film conductor for AlN ceramics Kurihara, Y.; Takahashi, S.; Yamada, K.; Endoh, T. Components, Hybrids, and Manufacturing Technology, IEEE Transactions on [see also IEEE Trans. on Components, Packaging, and Manufacturing Technology, Part A, B, C] Volume: 13 2, June 1990, Page(s): 306-312
PER			The influence of moisture on surface properties and insulation characteristics of AIN substrates Kurihara, Y.; Endoh, T.; Yamada, K. Components, Hybrids, and Manufacturing Technology, IEEE Transactions on [see also IEEE Trans. on Components, Packaging, and Manufacturing Technology, Part A, B, C] Volume: 12 3, Sept. 1989, Page(s): 330-334
PER	TITE		Processability of thin-film, fine-line pattern on aluminum nitride substrates (for hybrids) Chanchani, R. Components, Hybrids, and Manufacturing Technology, IEEE Transactions on [see also IEEE Trans. on Components, Packaging, and Manufacturing Technology, Part A, B, C] Volume: 11 4, Dec. 1988, Page(s): 427-432
PER	TOC		N/sub 2/ gas absorption in cathodic arc apparatus with an Alcathode under medium vacuum Takikawa, H.; Kawakami, N.; Sakakibara, T. Plasma Science, IEEE Transactions on





[Prev] 1 2 3 4 5 6 7 8

| IEL Online Home | Search | Advanced Search | What's New | Help | Logout | | FAQ's | Support | Comments |